



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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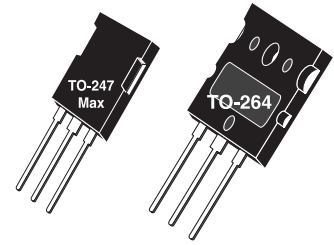
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## Ultra Fast NPT - IGBT®

The Ultra Fast NPT - IGBT® family of products is the newest generation of planar IGBTs optimized for outstanding ruggedness and the best trade-off between conduction and switching losses.



### Features

- Low Saturation Voltage
- Low Tail Current
- RoHS Compliant 
- Short Circuit Withstand Rated
- High Frequency Switching
- Ultra Low Leakage Current

Unless stated otherwise, Microsemi discrete IGBTs contain a single IGBT die. This device is recommended for applications such as induction heating (IH), motor control, general purpose inverters and uninterruptible power supplies (UPS).



### MAXIMUM RATINGS

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Ratings	Unit
$V_{ces}$	Collector Emitter Voltage	1200	V
$V_{GE}$	Gate-Emitter Voltage	$\pm 30$	
$I_{C1}$	Continuous Collector Current @ $T_C = 25^\circ\text{C}$	117	A
$I_{C2}$	Continuous Collector Current @ $T_C = 110^\circ\text{C}$	50	
$I_{CM}$	Pulsed Collector Current <sup>①</sup>	200	
SCWT	Short Circuit Withstand Time: $V_{CE} = 600V, V_{GE} = 15V, T_C = 125^\circ\text{C}$	10	$\mu\text{s}$
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	694	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_L$	Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.	300	

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Min	Typ	Max	Unit
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage ( $V_{GE} = 0V, I_C = 1.0mA$ )	1200			Volts
$V_{GE(TH)}$	Gate Threshold Voltage ( $V_{CE} = V_{GE}, I_C = 2.5mA, T_J = 25^\circ\text{C}$ )	3.5	5.0	6.5	
$V_{CE(ON)}$	Collector-Emitter On Voltage ( $V_{GE} = 15V, I_C = 50A, T_J = 25^\circ\text{C}$ )		2.5	3.2	
	Collector-Emitter On Voltage ( $V_{GE} = 15V, I_C = 50A, T_J = 125^\circ\text{C}$ )		3.3		
	Collector-Emitter On Voltage ( $V_{GE} = 15V, I_C = 100A, T_J = 25^\circ\text{C}$ )		3.5		
$I_{CES}$	Collector Cut-off Current ( $V_{CE} = 1200V, V_{GE} = 0V, T_J = 25^\circ\text{C}$ ) <sup>②</sup>		10	1000	$\mu\text{A}$
	Collector Cut-off Current ( $V_{CE} = 1200V, V_{GE} = 0V, T_J = 125^\circ\text{C}$ ) <sup>②</sup>		100		
$I_{GES}$	Gate-Emitter Leakage Current ( $V_{GE} = \pm 20V$ )			$\pm 250$	nA



**CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.**

# DYNAMIC CHARACTERISTICS

APT50GR120B2\_L

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$C_{ies}$	Input Capacitance	Capacitance $V_{GE} = 0V, V_{CE} = 25V$ $f = 1MHz$		5550		pF
$C_{oes}$	Output Capacitance			500		
$C_{res}$	Reverse Transfer Capacitance			145		
$V_{GEP}$	Gate to Emitter Plateau Voltage	Gate Charge $V_{GE} = 15V$ $V_{CE} = 600V$ $I_C = 50A$		7.5		V
$Q_g^{(3)}$	Total Gate Charge			330	445	
$Q_{ge}$	Gate-Emitter Charge			52	72	
$Q_{gc}$	Gate- Collector Charge			156	200	
$t_{d(on)}$	Turn-On Delay Time	Inductive Switching (25°C) $V_{CC} = 600V$ $V_{GE} = 15V$ $I_C = 50A$ $R_G = 4.3 \Omega^{(4)}$ $T_J = +25^\circ C$		28		ns
$t_r$	Current Rise Time			38		
$t_{d(off)}$	Turn-Off Delay Time			237		
$t_f$	Current Fall Time			45		
$E_{on2}^{(5)}$	Turn-On Switching Energy	Inductive Switching (25°C) $V_{CC} = 600V$ $V_{GE} = 15V$ $I_C = 50A$ $R_G = 4.3 \Omega^{(4)}$ $T_J = +25^\circ C$		2135	3200	μJ
$E_{off}^{(6)}$	Turn-Off Switching Energy			1478	2210	
$t_{d(on)}$	Turn-On Delay Time	Inductive Switching (125°C) $V_{CC} = 600V$ $V_{GE} = 15V$ $I_C = 50A$ $R_G = 4.3 \Omega^{(4)}$ $T_J = +125^\circ C$		28		ns
$t_r$	Current Rise Time			38		
$t_{d(off)}$	Turn-Off Delay Time			270		
$t_f$	Current Fall Time			54		
$E_{on2}^{(5)}$	Turn-On Switching Energy	Inductive Switching (125°C) $V_{CC} = 600V$ $V_{GE} = 15V$ $I_C = 50A$ $R_G = 4.3 \Omega^{(4)}$ $T_J = +125^\circ C$		3157	4765	μJ
$E_{off}^{(6)}$	Turn-Off Switching Energy			1884	2820	

# THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic	Min	Typ	Max	Unit
$R_{\theta JC}$	Junction to Case Thermal Resistance (IGBT)			.18	°C/W
$R_{\theta JA}$	Junction to Ambient Thermal Resistance			40	
$W_T$	Package Weight	B2	.22		oz
		L	6		g
		L	.36		oz
		L	10		g

- 1 Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.
  - 2 Pulse test: Pulse Width < 380μs, duty cycle < 2%.
  - 3 See Mil-Std-750 Method 3471.
  - 4  $R_G$  is external gate resistance, not including internal gate resistance or gate driver impedance. (MIC4452)
  - 5  $E_{on2}$  is the clamped inductive turn on energy that includes a commutating diode reverse recovery current in the IGBT turn on energy loss. A combi device is used for the clamping diode.
  - 6  $E_{off}$  is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1.
- Microsemi reserves the right to change, without notice, the specifications and information contained herein.

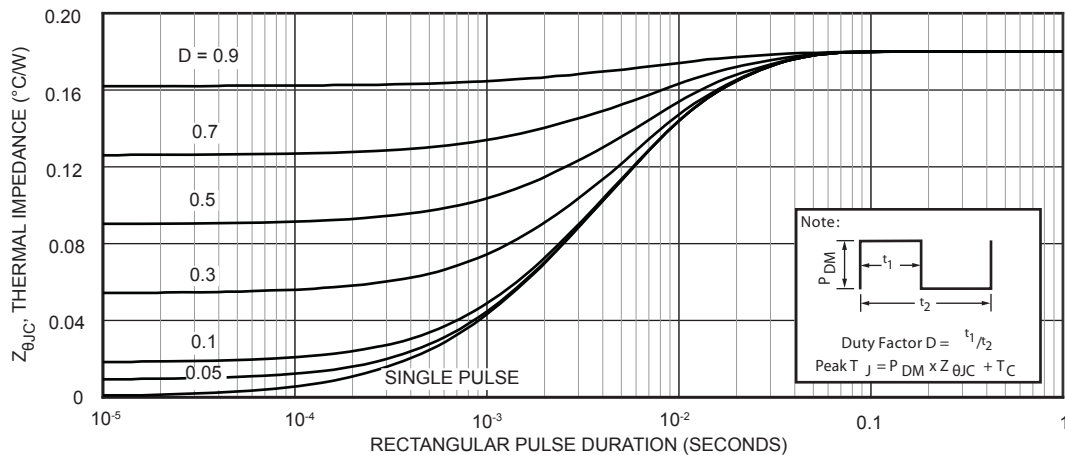
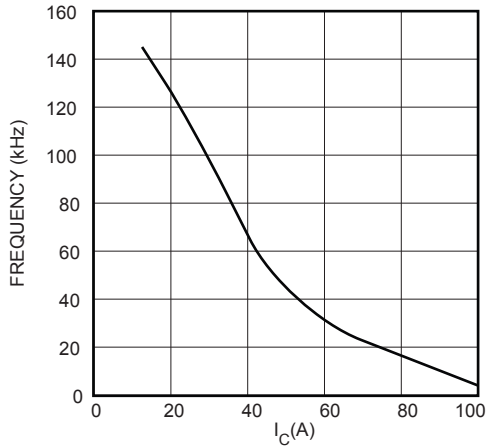


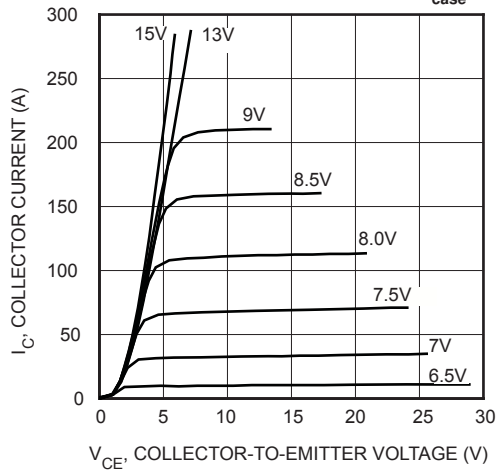
Figure 1, Maximum Effective Transient Thermal Impedance, Junction-To-Case vs Pulse Duration

**TYPICAL PERFORMANCE CURVES**

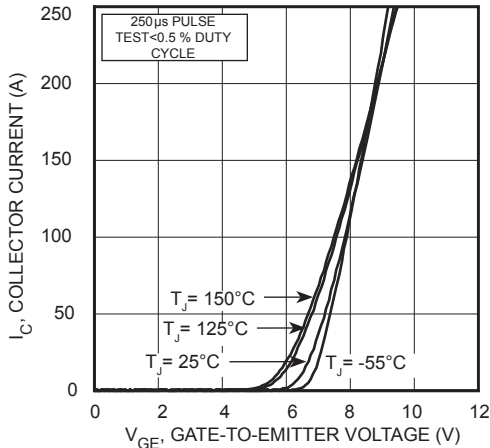
**APT50GR120B2\_L**



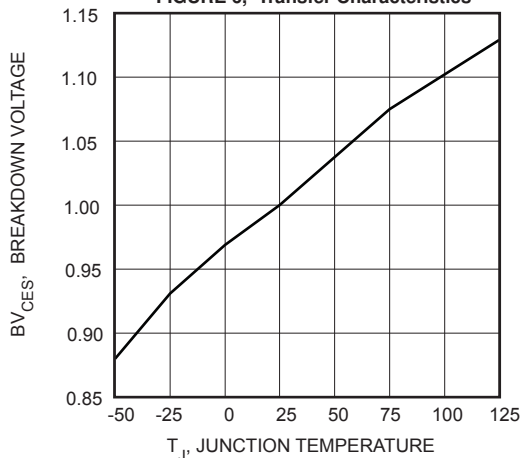
**FIGURE 2, Max Frequency vs Current ( $T_{case} = 75^{\circ}C$ )**



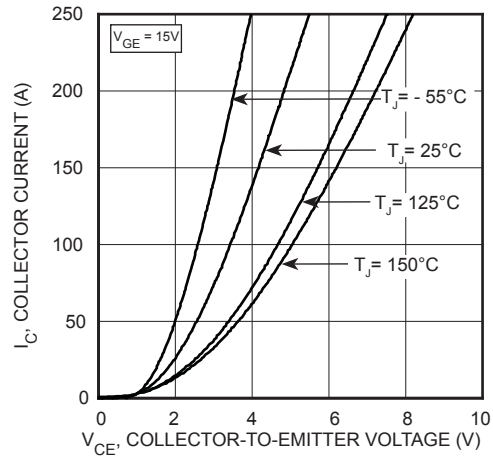
**FIGURE 4, Output Characteristics ( $T_J = 25^{\circ}C$ )**



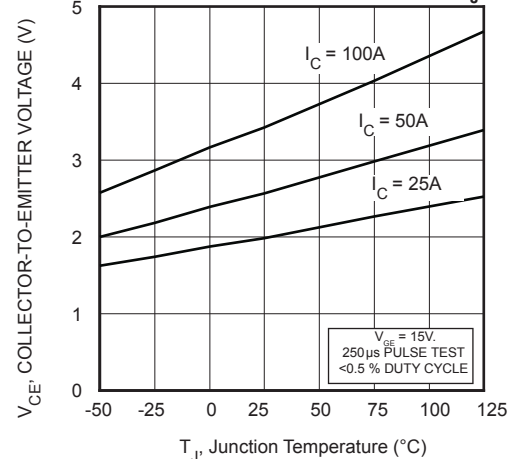
**FIGURE 6, Transfer Characteristics**



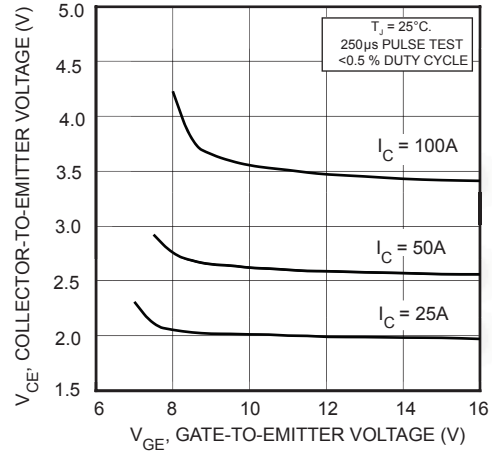
**FIGURE 8, Breakdown Voltage vs Junction Temperature**



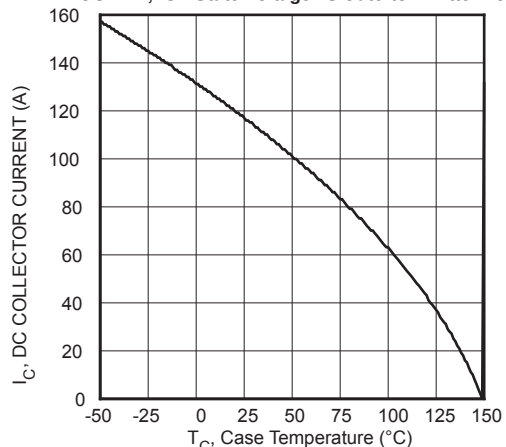
**FIGURE 3, Saturation Voltage Characteristics ( $T_J = 25^{\circ}C$ )**



**FIGURE 5, On State Voltage vs Junction Temperature**



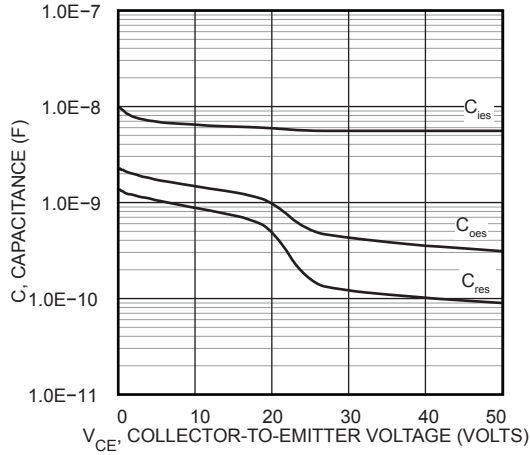
**FIGURE 7, On State Voltage vs Gate-to-Emitter Voltage**



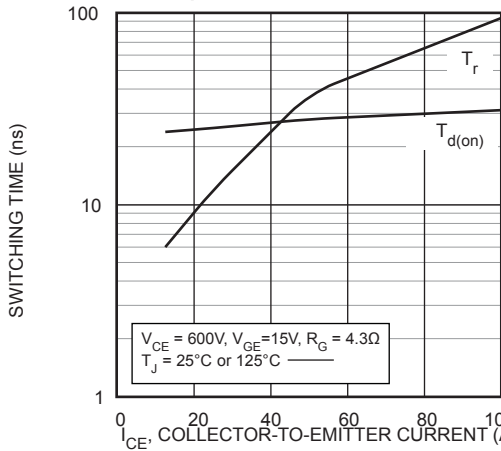
**FIGURE 9, DC Collector Current vs Case Temperature**

**TYPICAL PERFORMANCE CURVES**

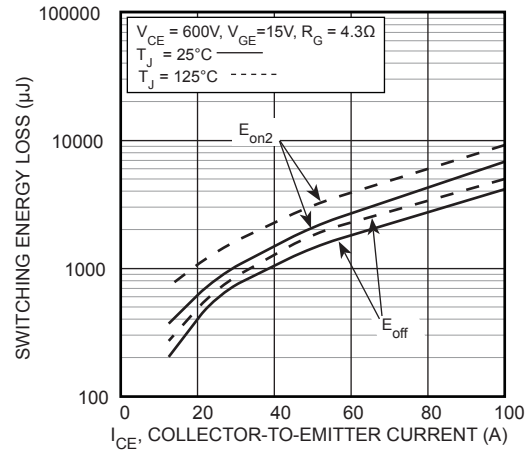
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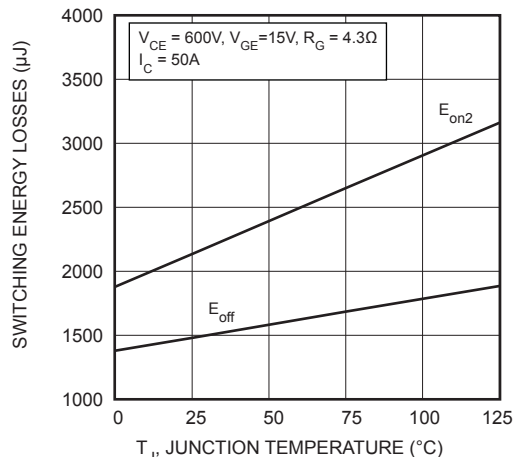
**FIGURE 10, Capacitance vs Collector-To-Emitter Voltage**



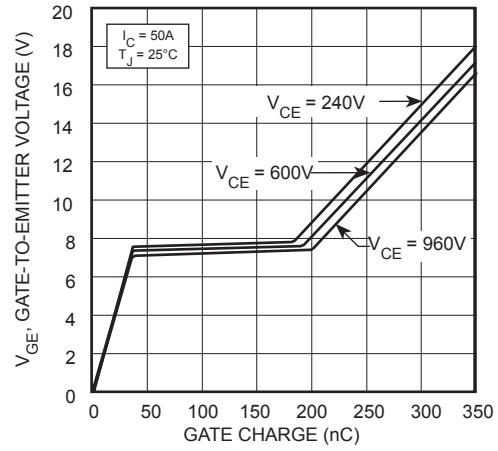
**FIGURE 12, Turn-On Time vs Collector Current**



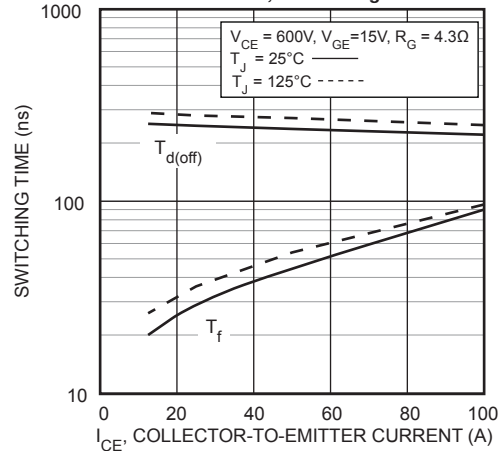
**FIGURE 14, Energy Loss vs Collector Current**



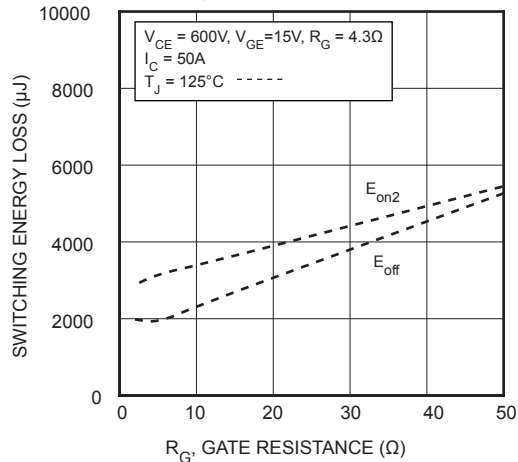
**FIGURE 16, Switching Energy vs Junction Temperature**



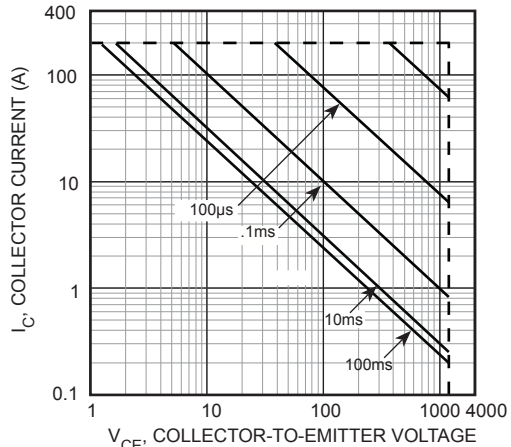
**FIGURE 11, Gate charge**



**FIGURE 13, Turn-Off Time vs Collector Current**

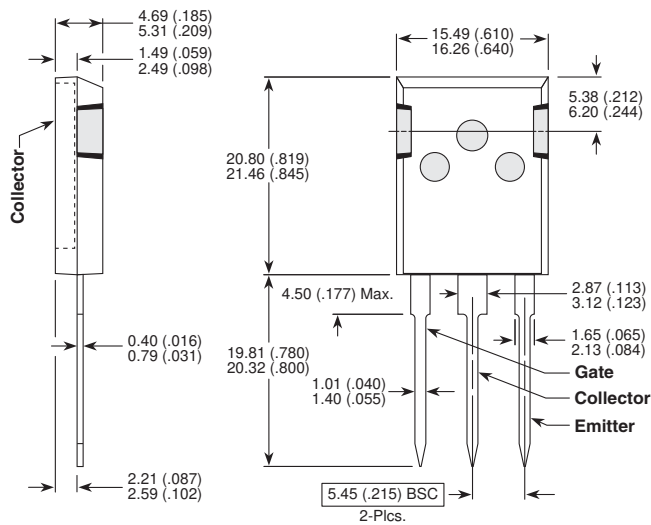


**FIGURE 15, Energy Loss vs Gate Resistance**



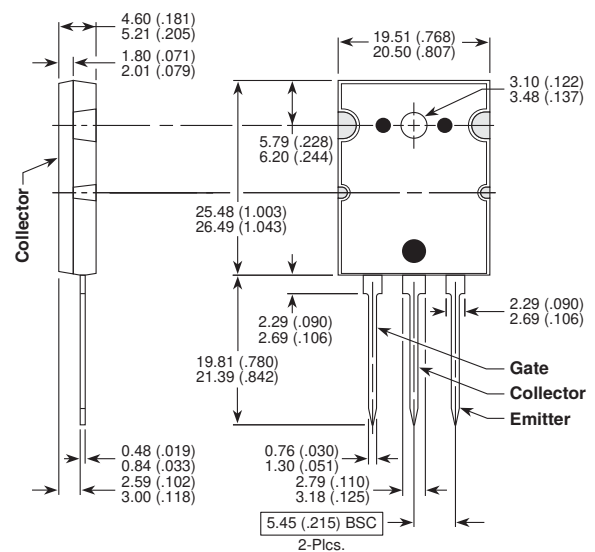
**FIGURE 17, Minimum Switching Safe Operating Area**

**T-MAX™ (B2) Package Outline**



These dimensions are equal to the TO-247 without the mounting hole.  
 Dimensions in Millimeters and (Inches)

**TO-264 (L) Package Outline**



Dimensions in Millimeters and (Inches)

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